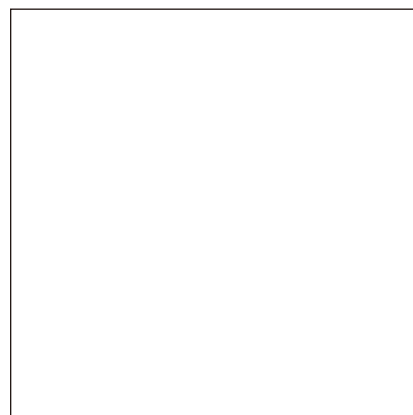
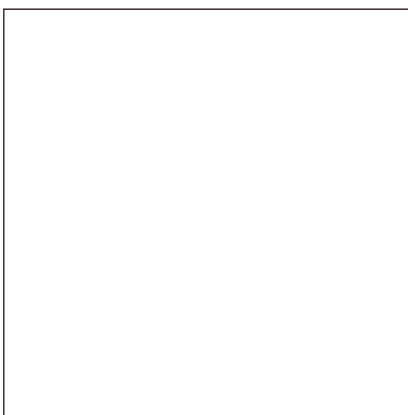
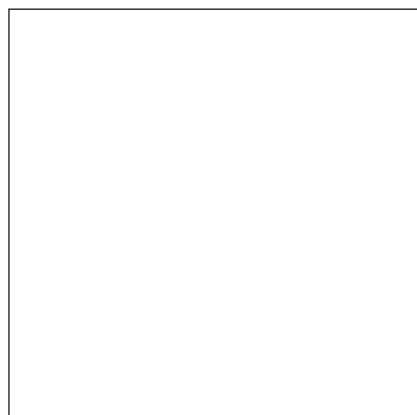
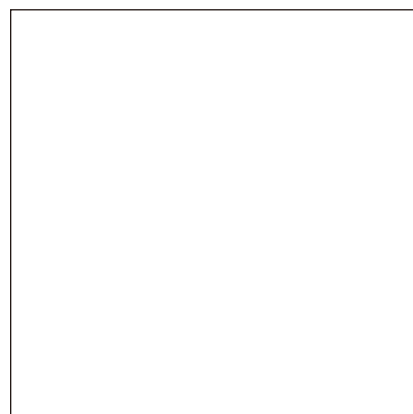
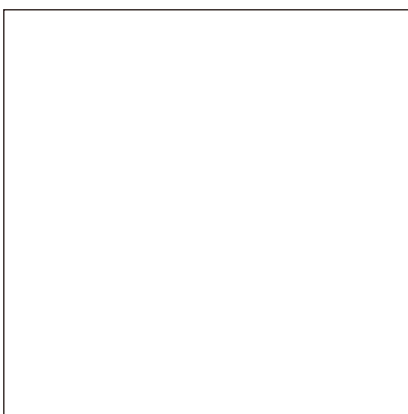
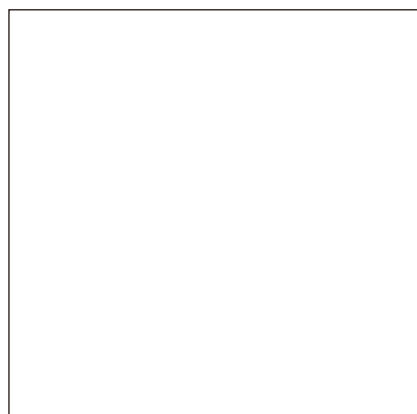
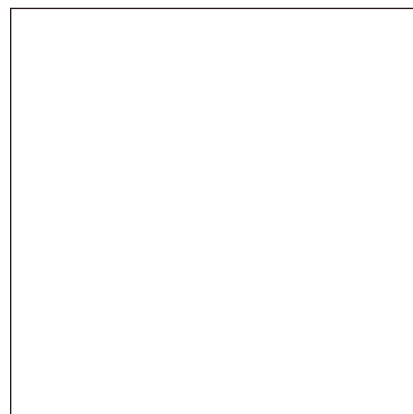
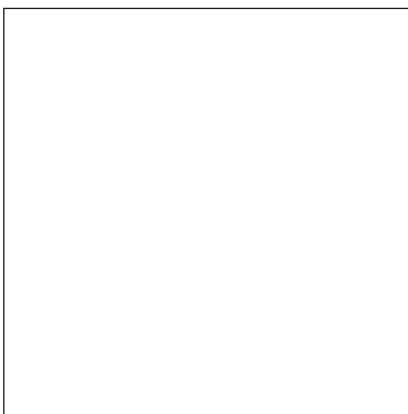
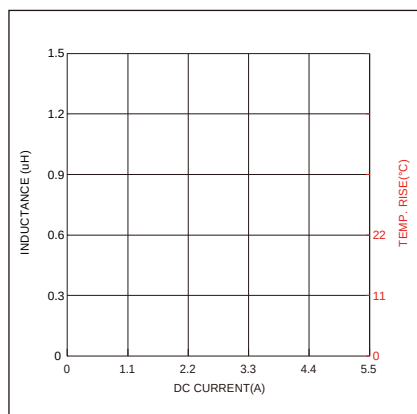
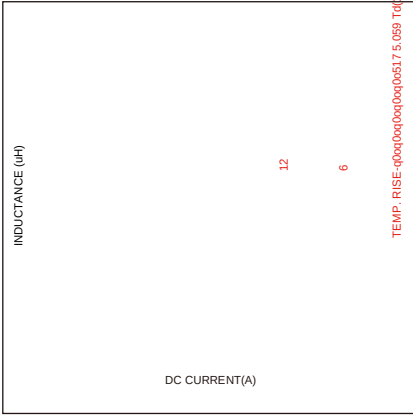
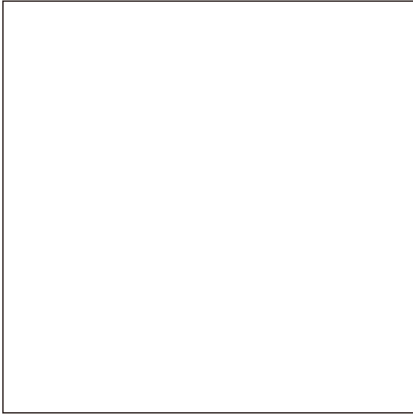
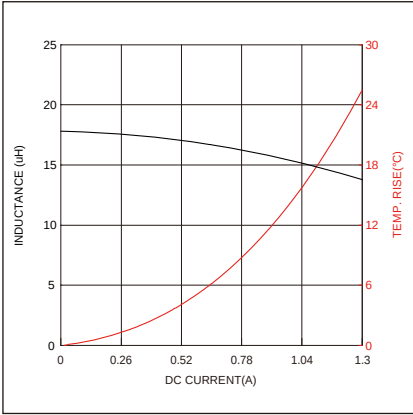
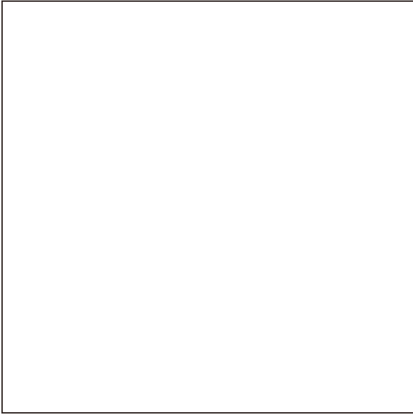
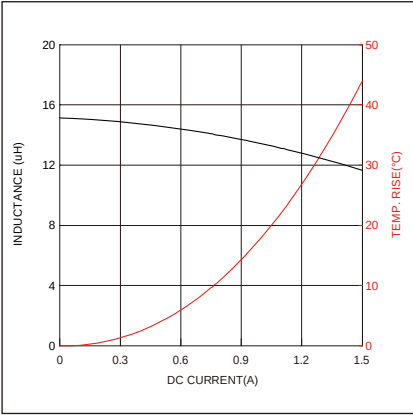




## Typical Electrical Characteristics:



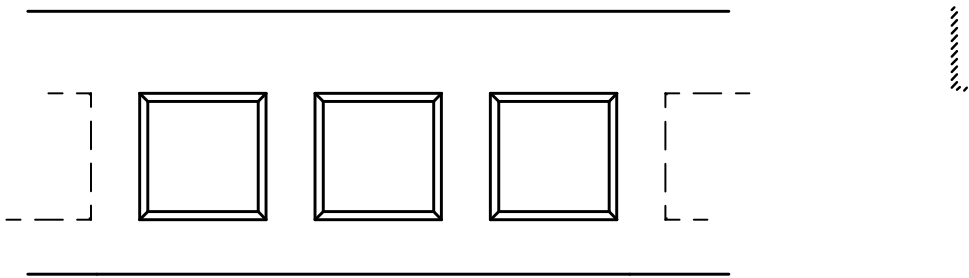


# Soldering Reflow:

Preheat condition: 150 ~200°C/ 60~120 sec.  
 Allowed time above 217°C: 60~90 sec.  
 Max temperature: 260°C.  
 Allowed Reflow time: 2x max.

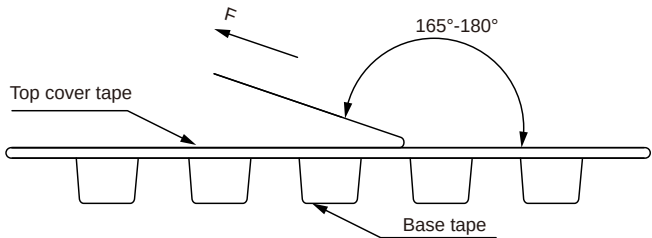
# Packaging Information:

Tape Dimension :



| Series   | A0<br>(mm) | B0<br>(mm) | D<br>(mm) | P0<br>(mm) | P1<br>(mm) | W<br>(mm) | K0<br>(mm) | E<br>(mm) | T<br>(mm) |
|----------|------------|------------|-----------|------------|------------|-----------|------------|-----------|-----------|
| NRSA5020 | 5.3±0.1    | 5.3±0.1    | 1.5±0.1   | 4.0±0.1    | 8.0±0.1    | 12.0±0.3  | 2.3±0.1    | 1.75±0.1  | 0.35±0.05 |

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.3 to 1.17 N

Reel Dimension : [mm]

Packaging Quantity: